

Abstract of the Disclosure

5           A method and apparatus electrically coupling  
input/output bond pads that are disposed proximate to one  
another on a microelectronic device. The apparatus  
includes a microelectronic device having at least two  
conductive input/output bond pads electrically coupled to  
an integrated circuit of the microelectronic device and  
first and second conductive stud balls bonded to first  
10 and second input/output pads, respectively, and a third  
conductive stud ball bonded to the first and second  
conductive stud balls. A wire bonding tool in "stud  
ball" mode is utilized to bond the conductive stud balls.